

Electronic Patent Application Fee Transmittal

Application Number:	10826713
Filing Date:	16-Apr-2004
Title of Invention:	Wafer-level assembly method for chip-size devices having flipped chips
First Named Inventor:	William D. Boyd
Filer:	Yingsheng Tung/Jackie McBride
Attorney Docket Number:	TI-37214

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	450	450

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				450